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#### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

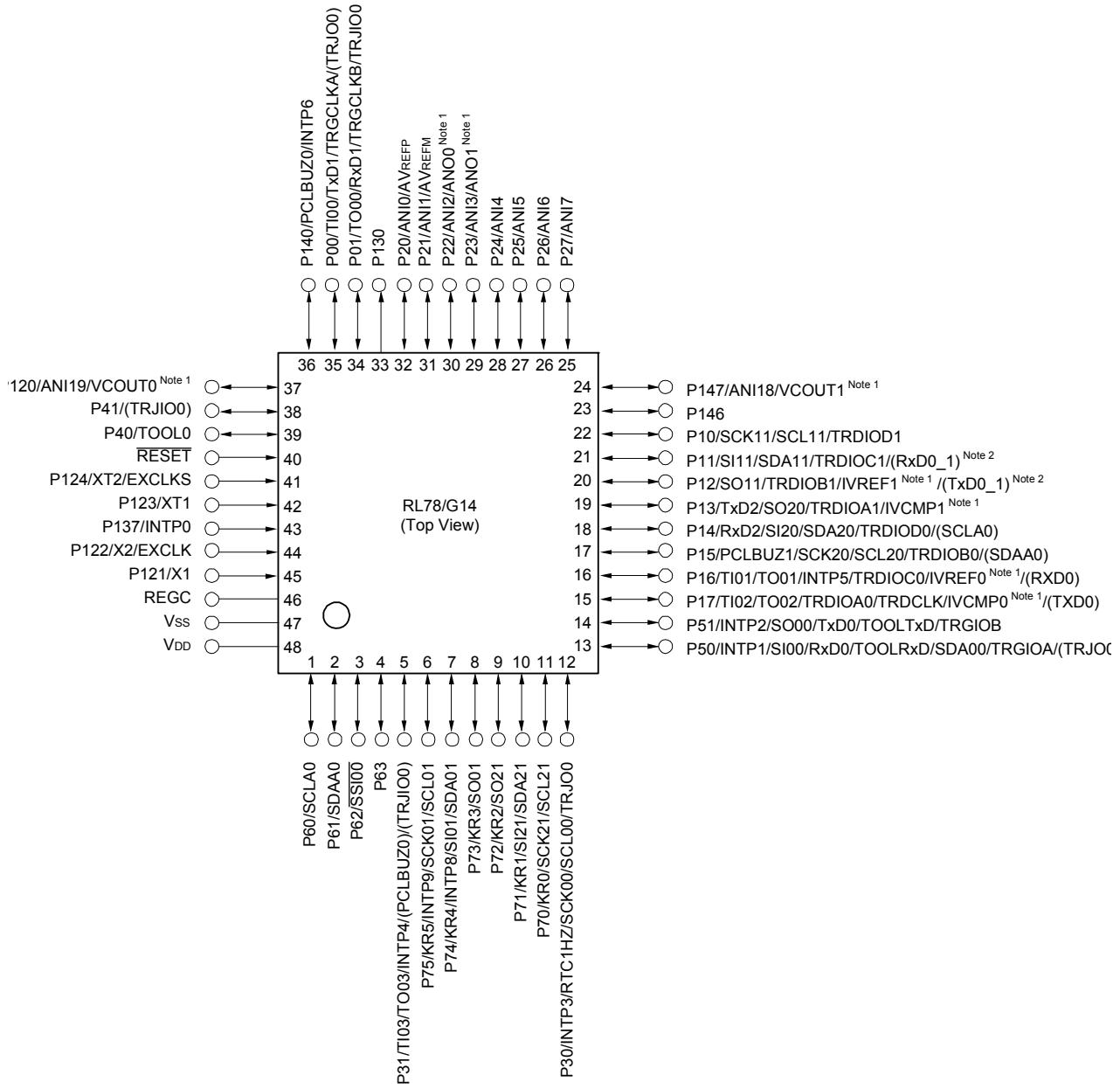
#### Applications of "[Embedded - Microcontrollers](#)"

##### Details

Product Status	Obsolete
Core Processor	RL78
Core Size	16-Bit
Speed	32MHz
Connectivity	CSI, I <sup>2</sup> C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 10x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-WFQFN Exposed Pad
Supplier Device Package	48-HWQFN (7x7)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f104gcana-u0">https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f104gcana-u0</a>

### 1.3.6 48-pin products

- 48-pin plastic LFQFP (7 × 7 mm, 0.5 mm pitch)



**Note 1.** Mounted on the 96 KB or more code flash memory products.

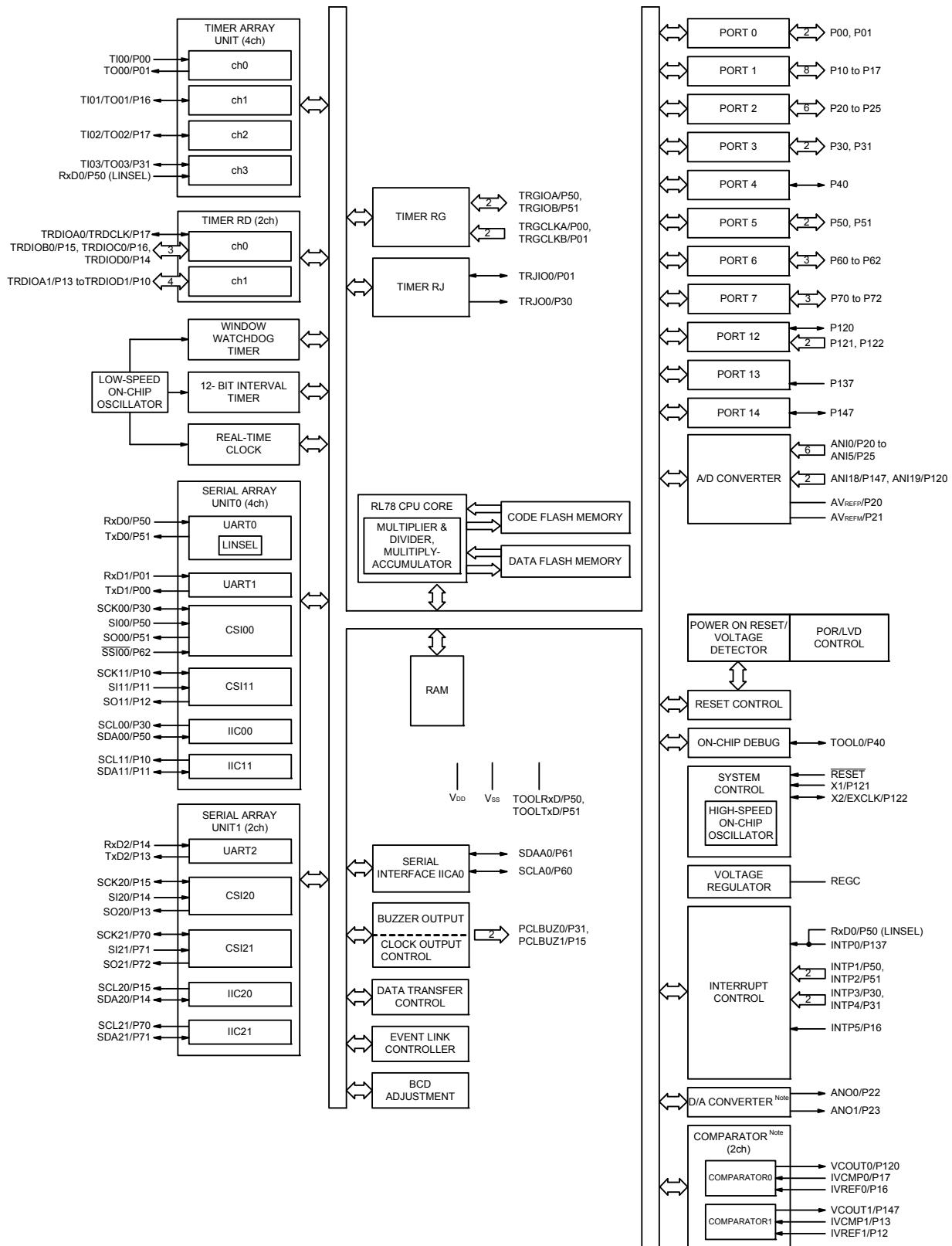
**Note 2.** Mounted on the 384 KB or more code flash memory products.

**Caution** Connect the REGC pin to Vss pin via a capacitor (0.47 to 1  $\mu$ F).

**Remark 1.** For pin identification, see 1.4 Pin Identification.

**Remark 2.** Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register 0, 1 (PIOR0, 1).

### 1.5.3 36-pin products



**Note** Mounted on the 96 KB or more code flash memory products.

**Note 1.** Total current flowing into V<sub>DD</sub>, EV<sub>DD0</sub>, and EV<sub>DD1</sub>, including the input leakage current flowing when the level of the input pin is fixed to V<sub>DD</sub>, EV<sub>DD0</sub>, and EV<sub>DD1</sub>, or V<sub>SS</sub>, EV<sub>VSS0</sub>, and EV<sub>VSS1</sub>. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, D/A converter, comparator, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.

**Note 2.** When high-speed on-chip oscillator and subsystem clock are stopped.

**Note 3.** When high-speed system clock and subsystem clock are stopped.

**Note 4.** When high-speed on-chip oscillator and high-speed system clock are stopped. When AMPHS1 = 1 (Ultra-low power consumption oscillation). However, not including the current flowing into the 12-bit interval timer and watchdog timer.

**Note 5.** Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (high-speed main) mode: 2.7 V ≤ V<sub>DD</sub> ≤ 5.5 V@1 MHz to 32 MHz

2.4 V ≤ V<sub>DD</sub> ≤ 5.5 V@1 MHz to 16 MHz

LS (low-speed main) mode: 1.8 V ≤ V<sub>DD</sub> ≤ 5.5 V@1 MHz to 8 MHz

LV (low-voltage main) mode: 1.6 V ≤ V<sub>DD</sub> ≤ 5.5 V@1 MHz to 4 MHz

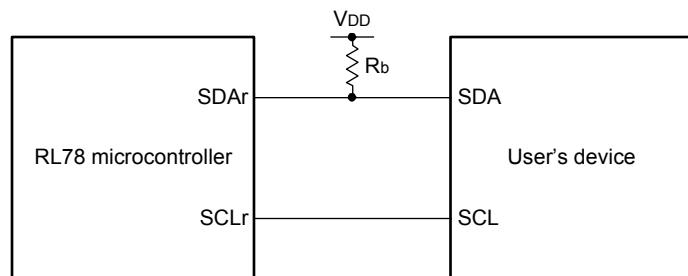
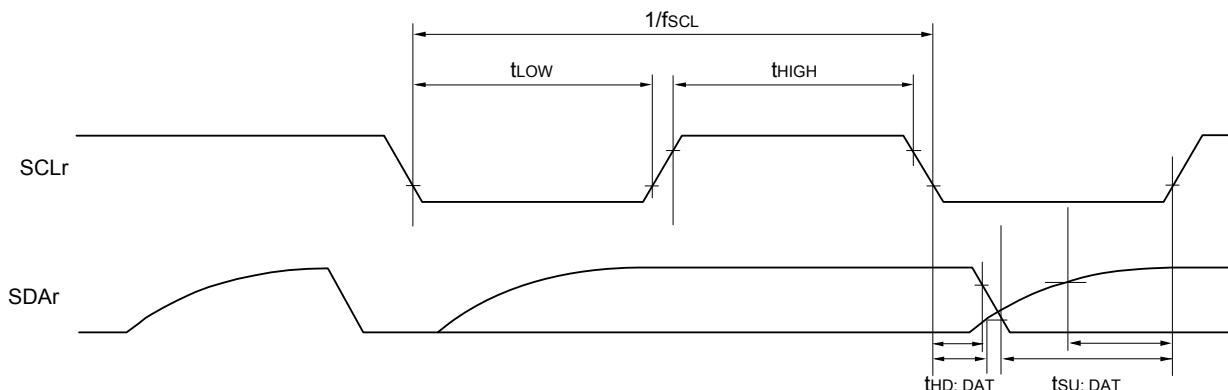
**Remark 1.** f<sub>MX</sub>: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

**Remark 2.** f<sub>HOCO</sub>: High-speed on-chip oscillator clock frequency (64 MHz max.)

**Remark 3.** f<sub>iH</sub>: High-speed on-chip oscillator clock frequency (32 MHz max.)

**Remark 4.** f<sub>SUB</sub>: Subsystem clock frequency (XT1 clock oscillation frequency)

**Remark 5.** Except subsystem clock operation, temperature condition of the TYP. value is TA = 25°C

**Simplified I<sup>2</sup>C mode connection diagram (during communication at same potential)****Simplified I<sup>2</sup>C mode serial transfer timing (during communication at same potential)**

**Remark 1.**  $R_b[\Omega]$ : Communication line (SDAr) pull-up resistance,  $C_b[F]$ : Communication line (SDAr, SCLr) load capacitance

**Remark 2.** r: IIC number ( $r = 00, 01, 10, 11, 20, 21, 30, 31$ ), g: PIM number ( $g = 0, 1, 3$  to  $5, 14$ ),

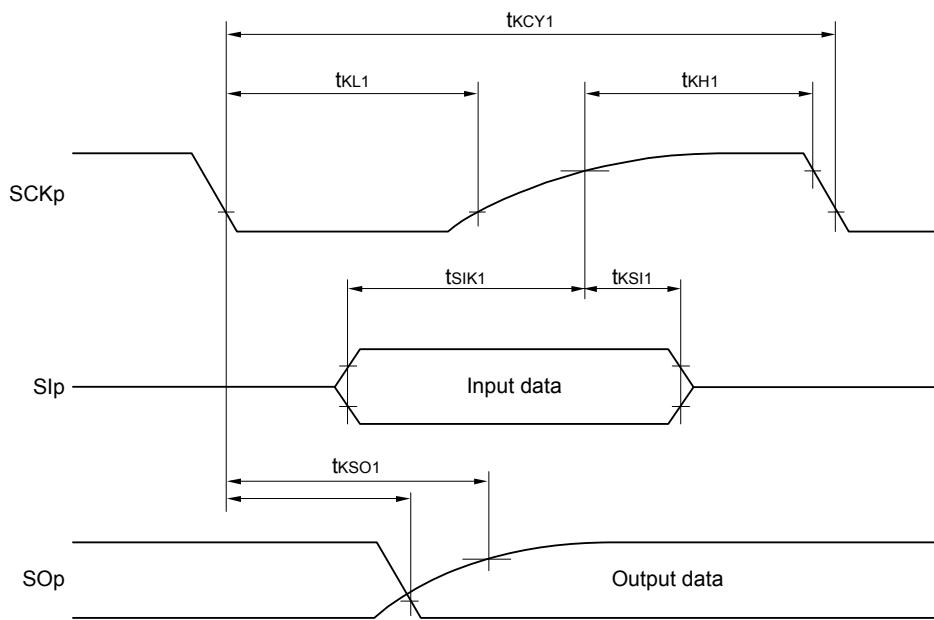
h: POM number ( $h = 0, 1, 3$  to  $5, 7, 14$ )

**Remark 3.**  $f_{MCK}$ : Serial array unit operation clock frequency

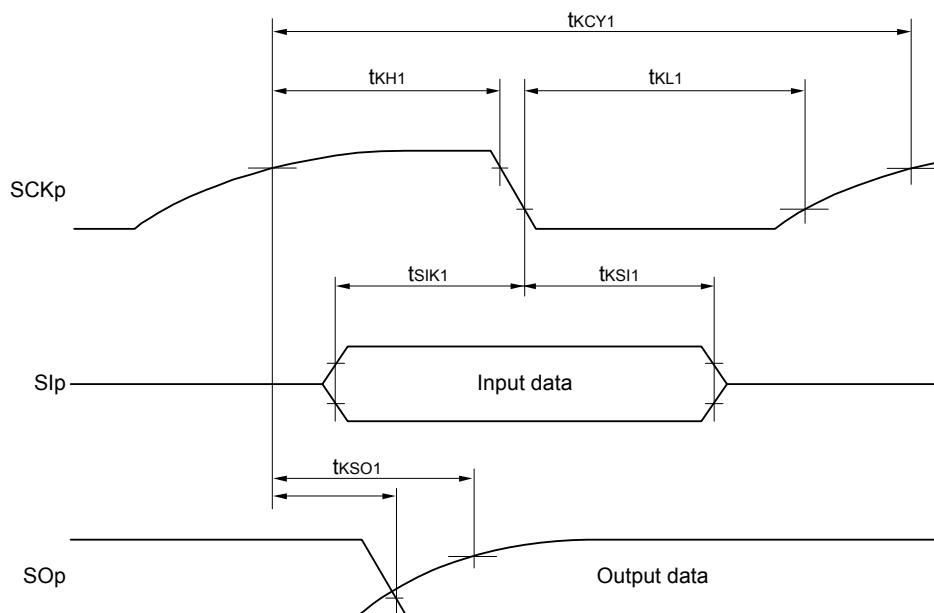
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number ( $m = 0, 1$ ),

n: Channel number ( $n = 0$  to  $3$ ), mn = 00 to 03, 10 to 13)

**CSI mode serial transfer timing (master mode) (during communication at different potential)**  
**(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)**



**CSI mode serial transfer timing (master mode) (during communication at different potential)**  
**(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)**



**Remark 1.** p: CSI number (p = 00, 01, 10, 20, 30, 31), m: Unit number (m = 0, 1), n: Channel number (n = 0 to 3),  
g: PIM and POM number (g = 0, 1, 3 to 5, 14)

**Remark 2.** CSI01 of 48-, 52-, 64-pin products, and CSI11 and CSI21 cannot communicate at different potential. Use other CSI for communication at different potential.

## 2.6.2 Temperature sensor characteristics/internal reference voltage characteristic

(TA = -40 to +85°C, 2.4 V ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V, HS (high-speed main) mode)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Temperature sensor output voltage	V <sub>TMPS25</sub>	Setting ADS register = 80H, TA = +25°C		1.05		V
Internal reference voltage	V <sub>BGR</sub>	Setting ADS register = 81H	1.38	1.45	1.5	V
Temperature coefficient	F <sub>VTMPS</sub>	Temperature sensor that depends on the temperature		-3.6		mV/°C
Operation stabilization wait time	t <sub>AMP</sub>		5			μs

## 2.6.3 D/A converter characteristics

(TA = -40 to +85°C, 1.6 V ≤ EV<sub>SS0</sub> = EV<sub>SS1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES					8	bit
Overall error	AINL	R <sub>load</sub> = 4 MΩ	1.8 V ≤ V <sub>DD</sub> ≤ 5.5 V			±2.5	LSB
		R <sub>load</sub> = 8 MΩ	1.8 V ≤ V <sub>DD</sub> ≤ 5.5 V			±2.5	LSB
Settling time	t <sub>SET</sub>	C <sub>load</sub> = 20 pF	2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V			3	μs
			1.6 V ≤ V <sub>DD</sub> < 2.7 V			6	μs

**(2) Interrupt & Reset Mode**

(TA = -40 to +85°C, VPDR ≤ VDD ≤ 5.5 V, Vss = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Voltage detection threshold	VLVDA0	VPOC2, VPOC1, VPOCO = 0, 0, 0, falling reset voltage		1.60	1.63	1.66	V
	VLVDA1	LVIS1, LVIS0 = 1, 0	Rising release reset voltage	1.74	1.77	1.81	V
			Falling interrupt voltage	1.70	1.73	1.77	V
	VLVDA2	LVIS1, LVIS0 = 0, 1	Rising release reset voltage	1.84	1.88	1.91	V
			Falling interrupt voltage	1.80	1.84	1.87	V
	VLVDA3	LVIS1, LVIS0 = 0, 0	Rising release reset voltage	2.86	2.92	2.97	V
			Falling interrupt voltage	2.80	2.86	2.91	V
	VLVDB0	VPOC2, VPOC1, VPOCO = 0, 0, 1, falling reset voltage		1.80	1.84	1.87	V
	VLVDB1	LVIS1, LVIS0 = 1, 0	Rising release reset voltage	1.94	1.98	2.02	V
			Falling interrupt voltage	1.90	1.94	1.98	V
	VLVDB2	LVIS1, LVIS0 = 0, 1	Rising release reset voltage	2.05	2.09	2.13	V
			Falling interrupt voltage	2.00	2.04	2.08	V
	VLVDB3	LVIS1, LVIS0 = 0, 0	Rising release reset voltage	3.07	3.13	3.19	V
			Falling interrupt voltage	3.00	3.06	3.12	V
Voltage detection threshold	VLVDC0	VPOC2, VPOC1, VPOCO = 0, 1, 0, falling reset voltage		2.40	2.45	2.50	V
	VLVDC1	LVIS1, LVIS0 = 1, 0	Rising release reset voltage	2.56	2.61	2.66	V
			Falling interrupt voltage	2.50	2.55	2.60	V
	VLVDC2	LVIS1, LVIS0 = 0, 1	Rising release reset voltage	2.66	2.71	2.76	V
			Falling interrupt voltage	2.60	2.65	2.70	V
	VLVDC3	LVIS1, LVIS0 = 0, 0	Rising release reset voltage	3.68	3.75	3.82	V
			Falling interrupt voltage	3.60	3.67	3.74	V
	VLVDD0	VPOC2, VPOC1, VPOCO = 0, 1, 1, falling reset voltage		2.70	2.75	2.81	V
	VLVDD1	LVIS1, LVIS0 = 1, 0	Rising release reset voltage	2.86	2.92	2.97	V
			Falling interrupt voltage	2.80	2.86	2.91	V
	VLVDD2	LVIS1, LVIS0 = 0, 1	Rising release reset voltage	2.96	3.02	3.08	V
			Falling interrupt voltage	2.90	2.96	3.02	V
	VLVDD3	LVIS1, LVIS0 = 0, 0	Rising release reset voltage	3.98	4.06	4.14	V
			Falling interrupt voltage	3.90	3.98	4.06	V

**2.6.7 Power supply voltage rising slope characteristics**

(TA = -40 to +85°C, Vss = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Power supply voltage rising slope	SVDD				54	V/ms

**Caution** Make sure to keep the internal reset state by the LVD circuit or an external reset until Vdd reaches the operating voltage range shown in 2.4 AC Characteristics.

### 3.1 Absolute Maximum Ratings

**Absolute Maximum Ratings** (1/2)

Parameter	Symbols	Conditions	Ratings	Unit
Supply voltage	V <sub>DD</sub>		-0.5 to +6.5	V
	EV <sub>DD0</sub> , EV <sub>DD1</sub>	EV <sub>DD0</sub> = EV <sub>DD1</sub>	-0.5 to +6.5	V
	EV <sub>SS0</sub> , EV <sub>SS1</sub>	EV <sub>SS0</sub> = EV <sub>SS1</sub>	-0.5 to +0.3	V
REGC pin input voltage	V <sub>IREGC</sub>	REGC	-0.3 to +2.8 and -0.3 to V <sub>DD</sub> +0.3 Note 1	V
Input voltage	V <sub>I1</sub>	P00 to P06, P10 to P17, P30, P31, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P100 to P102, P110, P111, P120, P140 to P147	-0.3 to EV <sub>DD0</sub> +0.3 and -0.3 to V <sub>DD</sub> +0.3 Note 2	V
	V <sub>I2</sub>	P60 to P63 (N-ch open-drain)	-0.3 to +6.5	V
	V <sub>I3</sub>	P20 to P27, P121 to P124, P137, P150 to P156, EXCLK, EXCLKS, <u>RESET</u>	-0.3 to V <sub>DD</sub> +0.3 Note 2	V
Output voltage	V <sub>O1</sub>	P00 to P06, P10 to P17, P30, P31, P40 to P47, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P100 to P102, P110, P111, P120, P130, P140 to P147	-0.3 to EV <sub>DD0</sub> +0.3 and -0.3 to V <sub>DD</sub> +0.3 Note 2	V
	V <sub>O2</sub>	P20 to P27, P150 to P156	-0.3 to V <sub>DD</sub> +0.3 Note 2	V
Analog input voltage	V <sub>AI1</sub>	ANI16 to ANI20	-0.3 to EV <sub>DD0</sub> +0.3 and -0.3 to AV <sub>REF</sub> (+) +0.3 Notes 2, 3	V
	V <sub>AI2</sub>	ANI0 to ANI14	-0.3 to V <sub>DD</sub> +0.3 and -0.3 to AV <sub>REF</sub> (+) +0.3 Notes 2, 3	V

**Note 1.** Connect the REGC pin to Vss via a capacitor (0.47 to 1  $\mu$ F). This value regulates the absolute maximum rating of the REGC pin. Do not use this pin with voltage applied to it.

**Note 2.** Must be 6.5 V or lower.

**Note 3.** Do not exceed AV<sub>REF</sub>(+) + 0.3 V in case of A/D conversion target pin.

**Caution** Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

**Remark 1.** Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

**Remark 2.** AV<sub>REF</sub>(+): + side reference voltage of the A/D converter.

**Remark 3.** V<sub>SS</sub>: Reference voltage

(TA = -40 to +105°C, 2.4 V ≤ EVDD0 = EVDD1 ≤ VDD ≤ 5.5 V, Vss = EVSS0 = EVSS1 = 0 V)

(2/5)

Items	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Output current, low Note 1	IOL1	Per pin for P00 to P06, P10 to P17, P30, P31, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P100 to P102, P110, P111, P120, P130, P140 to P147			8.5 Note 2	mA
		Per pin for P60 to P63			15.0 Note 2	mA
		Total of P00 to P04, P40 to P47, P102, P120, P130, P140 to P145 (When duty ≤ 70% Note 3)	4.0 V ≤ EVDD0 ≤ 5.5 V		40.0	mA
			2.7 V ≤ EVDD0 < 4.0 V		15.0	mA
			2.4 V ≤ EVDD0 < 2.7 V		9.0	mA
		Total of P05, P06, P10 to P17, P30, P31, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P100, P101, P110, P111, P146, P147 (When duty ≤ 70% Note 3)	4.0 V ≤ EVDD0 ≤ 5.5 V		40.0	mA
			2.7 V ≤ EVDD0 < 4.0 V		35.0	mA
			2.4 V ≤ EVDD0 < 2.7 V		20.0	mA
	IOL2	Total of all pins (When duty ≤ 70% Note 3)			80.0	mA
		Per pin for P20 to P27, P150 to P156			0.4 Note 2	mA
		Total of all pins (When duty ≤ 70% Note 3)	2.4 V ≤ VDD ≤ 5.5 V		5.0	mA

**Note 1.** Value of current at which the device operation is guaranteed even if the current flows from an output pin to the EVSS0, EVSS1, and Vss pins.

**Note 2.** Do not exceed the total current value.

**Note 3.** Specification under conditions where the duty factor ≤ 70%.

The output current value that has changed to the duty factor > 70% the duty ratio can be calculated with the following expression (when changing the duty factor from 70% to n%).

- Total output current of pins =  $(I_{OL} \times 0.7)/(n \times 0.01)$

<Example> Where n = 80% and IOL = 10.0 mA

$$\text{Total output current of pins} = (10.0 \times 0.7)/(80 \times 0.01) \approx 8.7 \text{ mA}$$

However, the current that is allowed to flow into one pin does not vary depending on the duty factor.

A current higher than the absolute maximum rating must not flow into one pin.

**Remark** Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

**Note 1.** Total current flowing into V<sub>DD</sub> and EV<sub>DD0</sub>, including the input leakage current flowing when the level of the input pin is fixed to V<sub>DD</sub>, EV<sub>DD0</sub> or V<sub>SS</sub>, EV<sub>SS0</sub>. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.

**Note 2.** When high-speed on-chip oscillator and subsystem clock are stopped.

**Note 3.** When high-speed system clock and subsystem clock are stopped.

**Note 4.** When high-speed on-chip oscillator and high-speed system clock are stopped. When AMPHS1 = 1 (Ultra-low power consumption oscillation). However, not including the current flowing into the RTC, 12-bit interval timer, and watchdog timer.

**Note 5.** Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (high-speed main) mode: 2.7 V ≤ V<sub>DD</sub> ≤ 5.5 V@1 MHz to 32 MHz

2.4 V ≤ V<sub>DD</sub> ≤ 5.5 V@1 MHz to 16 MHz

**Remark 1.** f<sub>MX</sub>: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

**Remark 2.** f<sub>HOCO</sub>: High-speed on-chip oscillator clock frequency (64 MHz max.)

**Remark 3.** f<sub>iH</sub>: High-speed on-chip oscillator clock frequency (32 MHz max.)

**Remark 4.** f<sub>SUB</sub>: Subsystem clock frequency (XT1 clock oscillation frequency)

**Remark 5.** Except subsystem clock operation, temperature condition of the TYP. value is TA = 25°C

**(2) Flash ROM: 96 to 256 KB of 30- to 100-pin products**(TA = -40 to +105°C, 2.4 V ≤ EV<sub>VDD0</sub> = EV<sub>VDD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>VSS0</sub> = EV<sub>VSS1</sub> = 0 V)

Parameter	Symbol	Conditions					MIN.	TYP.	MAX.	Unit
Supply current Note 1	I <sub>DD1</sub>	Operating mode HS (high-speed main) mode Note 5	f <sub>HOCO</sub> = 64 MHz, f <sub>lH</sub> = 32 MHz Note 3	Basic operation	V <sub>DD</sub> = 5.0 V		2.6			mA
					V <sub>DD</sub> = 3.0 V		2.6			
			f <sub>HOCO</sub> = 32 MHz, f <sub>lH</sub> = 32 MHz Note 3	Basic operation	V <sub>DD</sub> = 5.0 V		2.3			
					V <sub>DD</sub> = 3.0 V		2.3			
		HS (high-speed main) mode Note 5	f <sub>HOCO</sub> = 64 MHz, f <sub>lH</sub> = 32 MHz Note 3	Normal operation	V <sub>DD</sub> = 5.0 V		5.4	10.9		mA
					V <sub>DD</sub> = 3.0 V		5.4	10.9		
			f <sub>HOCO</sub> = 32 MHz, f <sub>lH</sub> = 32 MHz Note 3	Normal operation	V <sub>DD</sub> = 5.0 V		5.0	10.3		
					V <sub>DD</sub> = 3.0 V		5.0	10.3		
			f <sub>HOCO</sub> = 48 MHz, f <sub>lH</sub> = 24 MHz Note 3	Normal operation	V <sub>DD</sub> = 5.0 V		4.2	8.2		
					V <sub>DD</sub> = 3.0 V		4.2	8.2		
		HS (high-speed main) mode Note 5	f <sub>HOCO</sub> = 24 MHz, f <sub>lH</sub> = 24 MHz Note 3	Normal operation	V <sub>DD</sub> = 5.0 V		4.0	7.8		mA
					V <sub>DD</sub> = 3.0 V		4.0	7.8		
			f <sub>HOCO</sub> = 16 MHz, f <sub>lH</sub> = 16 MHz Note 3	Normal operation	V <sub>DD</sub> = 5.0 V		3.0	5.6		
					V <sub>DD</sub> = 3.0 V		3.0	5.6		
			f <sub>MX</sub> = 20 MHz Note 2, V <sub>DD</sub> = 5.0 V	Normal operation	Square wave input		3.4	6.6		mA
					Resonator connection		3.6	6.7		
		Subsystem clock operation	f <sub>MX</sub> = 20 MHz Note 2, V <sub>DD</sub> = 3.0 V	Normal operation	Square wave input		3.4	6.6		
					Resonator connection		3.6	6.7		
			f <sub>MX</sub> = 10 MHz Note 2, V <sub>DD</sub> = 5.0 V	Normal operation	Square wave input		2.1	3.9		
					Resonator connection		2.2	4.0		
			f <sub>MX</sub> = 10 MHz Note 2, V <sub>DD</sub> = 3.0 V	Normal operation	Square wave input		2.1	3.9		μA
					Resonator connection		2.2	4.0		
			f <sub>SUB</sub> = 32.768 kHz Note 4 TA = -40°C	Normal operation	Square wave input		4.9	7.1		
					Resonator connection		4.9	7.1		
			f <sub>SUB</sub> = 32.768 kHz Note 4 TA = +25°C	Normal operation	Square wave input		4.9	7.1		
					Resonator connection		4.9	7.1		
			f <sub>SUB</sub> = 32.768 kHz Note 4 TA = +50°C	Normal operation	Square wave input		5.1	8.8		
					Resonator connection		5.1	8.8		
			f <sub>SUB</sub> = 32.768 kHz Note 4 TA = +70°C	Normal operation	Square wave input		5.5	10.5		
					Resonator connection		5.5	10.5		
			f <sub>SUB</sub> = 32.768 kHz Note 4 TA = +85°C	Normal operation	Square wave input		6.5	14.5		
					Resonator connection		6.5	14.5		
			f <sub>SUB</sub> = 32.768 kHz Note 4 TA = +105°C	Normal operation	Square wave input		13.0	58.0		
					Resonator connection		13.0	58.0		

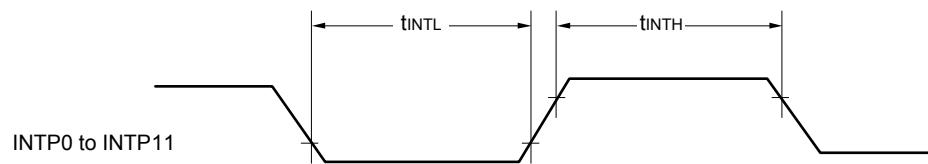
(Notes and Remarks are listed on the next page.)

(TA = -40 to +105°C, 2.4 V ≤ EVDD0 = EVDD1 ≤ VDD ≤ 5.5 V, VSS = EVSS0 = EVSS1 = 0 V)

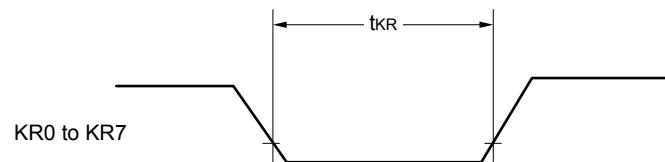
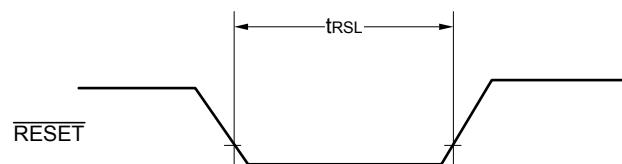
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Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Timer RD input high-level width, low-level width	tTDIH, tTDIL	TRDIOA0, TRDIOA1, TRDIOB0, TRDIOB1, TRDIODC0, TRDIODC1, TRDIOD0, TRDIOD1		3/fCLK			ns
Timer RD forced cutoff signal input low-level width	tTDSIL	P130/INTP0	2MHz < fCLK ≤ 32 MHz	1			μs
			fCLK ≤ 2 MHz	1/fCLK + 1			
Timer RG input high-level width, low-level width	tTRGIH, tTGIL	TRGIOA, TRGIOB		2.5/fCLK			ns
TO00 to TO03, TO10 to TO13, TRJIO0, TRJOO, TRDIOA0, TRDIOA1, TRDIOB0, TRDIOB1, TRDIODC0, TRDIODC1, TRDIOD0, TRDIOD1, TRGIOA, TRGIOB output frequency	fro	HS (high-speed main) mode	4.0 V ≤ EVDD0 ≤ 5.5 V			16	MHz
			2.7 V ≤ EVDD0 < 4.0 V			8	MHz
			2.4 V ≤ EVDD0 < 2.7 V			4	MHz
PCLBUZ0, PCLBUZ1 output frequency	fpCL	HS (high-speed main) mode	4.0 V ≤ EVDD0 ≤ 5.5 V			16	MHz
			2.7 V ≤ EVDD0 < 4.0 V			8	MHz
			2.4 V ≤ EVDD0 < 2.7 V			4	MHz
Interrupt input high-level width, low-level width	tINTH, tINTL	INTP0	2.4 V ≤ VDD ≤ 5.5 V	1			μs
		INTP1 to INTP11	2.4 V ≤ EVDD0 ≤ 5.5 V	1			μs
Key interrupt input low-level width	tKR	KR0 to KR7	2.4 V ≤ EVDD0 ≤ 5.5 V	250			ns
RESET low-level width	tRSI			10			μs

## Interrupt Request Input Timing



## Key Interrupt Input Timing

 $\overline{\text{RESET}}$  Input Timing

**(2) During communication at same potential (CSI mode) (master mode, SCKp... internal clock output)**(TA = -40 to +105°C, 2.4 V ≤ EV<sub>DD0</sub> = EV<sub>DD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) mode		Unit
				MIN.	MAX.	
SCKp cycle time	tkCY1	tkCY1 ≥ 4/fCLK	2.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	250		ns
			2.4 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	500		ns
SCKp high-/low-level width	tKH1, tKL1	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		tkCY1/2 - 24		ns
		2.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		tkCY1/2 - 36		ns
		2.4 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		tkCY1/2 - 76		ns
Slp setup time (to SCKp↑) Note 1	tSIK1	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		66		ns
		2.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		66		ns
		2.4 V ≤ EV <sub>DD0</sub> ≤ 5.5 V		113		ns
Slp hold time (from SCKp↓) Note 2	tSIS1			38		ns
Delay time from SCKp↓ to SOp output Note 3	tKS01	C = 30 pF Note 4			50	ns

**Note 1.** When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The Slp setup time becomes “to SCKp↓” when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

**Note 2.** When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The Slp hold time becomes “from SCKp↓” when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

**Note 3.** When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes “from SCKp↑” when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

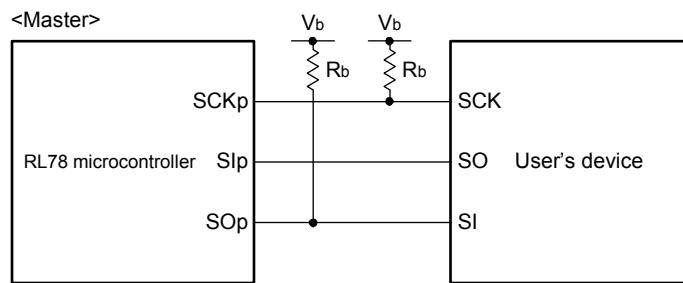
**Note 4.** C is the load capacitance of the SCKp and SOp output lines.

**Caution** Select the normal input buffer for the Slp pin and the normal output mode for the SOp pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg).

**Remark 1.** p: CSI number (p = 00, 01, 10, 11, 20, 21, 30, 31), m: Unit number (m = 0, 1), n: Channel number (n = 0 to 3), g: PIM number (g = 0, 1, 3 to 5, 14)

**Remark 2.** fmCK: Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13))

**CSI mode connection diagram (during communication at different potential)**

**Remark 5.** R<sub>b</sub>[Ω]: Communication line (SCKp, SOp) pull-up resistance, C<sub>b</sub>[F]: Communication line (SCKp, SOp) load capacitance, V<sub>b</sub>[V]: Communication line voltage

**Remark 6.** p: CSI number (p = 00, 01, 10, 20, 30, 31), m: Unit number (m = 0, 1), n: Channel number (n = 0 to 3), g: PIM and POM number (g = 0, 1, 3 to 5, 14)

**Remark 7.** fmck: Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00))

**Remark 8.** CSI01 of 48-, 52-, 64-pin products, and CSI11 and CSI21 cannot communicate at different potential. Use other CSI for communication at different potential.

## 3.6 Analog Characteristics

### 3.6.1 A/D converter characteristics

#### Classification of A/D converter characteristics

Input channel	Reference Voltage Reference voltage (+) = AVREFP Reference voltage (-) = AVREFM	Reference voltage (+) = VDD Reference voltage (-) = VSS	Reference voltage (+) = VBGR Reference voltage (-) = AVREFM
AN10 to AN14	Refer to 3.6.1 (1).	Refer to 3.6.1 (3).	Refer to 3.6.1 (4).  —
AN16 to AN20	Refer to 3.6.1 (2).		
Internal reference voltage Temperature sensor output voltage	Refer to 3.6.1 (1).		

- (1) When reference voltage (+) = AVREFP/AN10 (ADREFP1 = 0, ADREFP0 = 1), reference voltage (-) = AVREFM/AN11 (ADREFM = 1), target pin: AN12 to AN14, internal reference voltage, and temperature sensor output voltage

(TA = -40 to +105°C, 2.4 V ≤ AVREFP ≤ VDD ≤ 5.5 V, VSS = 0 V, Reference voltage (+) = AVREFP,

Reference voltage (-) = AVREFM = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error Note 1	AINL	10-bit resolution AVREFP = VDD Note 3	2.4 V ≤ AVREFP ≤ 5.5 V		1.2	±3.5	LSB
Conversion time	tCONV	10-bit resolution Target pin: AN12 to AN14	3.6 V ≤ VDD ≤ 5.5 V	2.125		39	μs
			2.7 V ≤ VDD ≤ 5.5 V	3.1875		39	μs
			2.4 V ≤ VDD ≤ 5.5 V	17		39	μs
		10-bit resolution Target pin: Internal reference voltage, and temperature sensor output voltage (HS (high-speed main) mode)	3.6 V ≤ VDD ≤ 5.5 V	2.375		39	μs
			2.7 V ≤ VDD ≤ 5.5 V	3.5625		39	μs
			2.4 V ≤ VDD ≤ 5.5 V	17		39	μs
Zero-scale error Notes 1, 2	Ezs	10-bit resolution AVREFP = VDD Note 3	2.4 V ≤ AVREFP ≤ 5.5 V			±0.25	%FSR
Full-scale error Notes 1, 2	EFS	10-bit resolution AVREFP = VDD Note 3	2.4 V ≤ AVREFP ≤ 5.5 V			±0.25	%FSR
Integral linearity error Note 1	ILE	10-bit resolution AVREFP = VDD Note 3	2.4 V ≤ AVREFP ≤ 5.5 V			±2.5	LSB
Differential linearity error Note 1	DLE	10-bit resolution AVREFP = VDD Note 3	2.4 V ≤ AVREFP ≤ 5.5 V			±1.5	LSB
Analog input voltage	VAIN	ANI2 to ANI14		0		AVREFP	V
		Internal reference voltage output (2.4 V ≤ VDD ≤ 5.5 V, HS (high-speed main) mode)			VBGR Note 4		V
		Temperature sensor output voltage (2.4 V ≤ VDD ≤ 5.5 V, HS (high-speed main) mode)			VTMPS25 Note 4		V

Note 1. Excludes quantization error (±1/2 LSB).

Note 2. This value is indicated as a ratio (%FSR) to the full-scale value.

Note 3. When AVREFP < VDD, the MAX. values are as follows.

Overall error: Add ±1.0 LSB to the MAX. value when AVREFP = VDD.

Zero-scale error/Full-scale error: Add ±0.05%FSR to the MAX. value when AVREFP = VDD.

Integral linearity error/ Differential linearity error: Add ±0.5 LSB to the MAX. value when AVREFP = VDD.

Note 4. Refer to 3.6.2 Temperature sensor characteristics/internal reference voltage characteristic.

- (3) When reference voltage (+) = V<sub>DD</sub> (ADREFP1 = 0, ADREFP0 = 0), reference voltage (-) = V<sub>SS</sub> (ADREFM = 0), target pin: ANI0 to ANI14, ANI16 to ANI20, internal reference voltage, and temperature sensor output voltage

(TA = -40 to +105°C, 2.4 V ≤ EV<sub>DD0</sub> = EV<sub>DD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V, Reference voltage (+) = V<sub>DD</sub>, Reference voltage (-) = V<sub>SS</sub>)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Resolution	RES		8		10	bit
Overall error Note 1	AINL	10-bit resolution	2.4 V ≤ V <sub>DD</sub> ≤ 5.5 V		1.2	±7.0 LSB
Conversion time	t <sub>CONV</sub>	10-bit resolution Target pin: ANI0 to ANI14, ANI16 to ANI20	3.6 V ≤ V <sub>DD</sub> ≤ 5.5 V	2.125		39 μs
			2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V	3.1875		39 μs
			2.4 V ≤ V <sub>DD</sub> ≤ 5.5 V	17		39 μs
		10-bit resolution Target pin: internal reference voltage, and temperature sensor output voltage (HS (high-speed main) mode)	3.6 V ≤ V <sub>DD</sub> ≤ 5.5 V	2.375		39 μs
			2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V	3.5625		39 μs
			2.4 V ≤ V <sub>DD</sub> ≤ 5.5 V	17		39 μs
Zero-scale error Notes 1, 2	E <sub>ZS</sub>	10-bit resolution	2.4 V ≤ V <sub>DD</sub> ≤ 5.5 V			±0.60 %FSR
Full-scale error Notes 1, 2	E <sub>FS</sub>	10-bit resolution	2.4 V ≤ V <sub>DD</sub> ≤ 5.5 V			±0.60 %FSR
Integral linearity error Note 1	I <sub>LE</sub>	10-bit resolution	2.4 V ≤ V <sub>DD</sub> ≤ 5.5 V			±4.0 LSB
Differential linearity error Note 1	D <sub>LE</sub>	10-bit resolution	2.4 V ≤ V <sub>DD</sub> ≤ 5.5 V			±2.0 LSB
Analog input voltage	V <sub>AIN</sub>	ANI0 to ANI14		0		V <sub>DD</sub> V
		ANI16 to ANI20		0		EV <sub>DD0</sub> V
		Internal reference voltage (2.4 V ≤ V <sub>DD</sub> ≤ 5.5 V, HS (high-speed main) mode)		V <sub>BGR</sub> Note 3		V
		Temperature sensor output voltage (2.4 V ≤ V <sub>DD</sub> ≤ 5.5 V, HS (high-speed main) mode)		V <sub>TMP525</sub> Note 3		V

Note 1. Excludes quantization error (±1/2 LSB).

Note 2. This value is indicated as a ratio (% FSR) to the full-scale value.

Note 3. Refer to 3.6.2 Temperature sensor characteristics/internal reference voltage characteristic.

### 3.6.2 Temperature sensor characteristics/internal reference voltage characteristic

(TA = -40 to +105°C, 2.4 V ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V, HS (high-speed main) mode)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Temperature sensor output voltage	V <sub>TMPS25</sub>	Setting ADS register = 80H, TA = +25°C		1.05		V
Internal reference voltage	V <sub>BGR</sub>	Setting ADS register = 81H	1.38	1.45	1.5	V
Temperature coefficient	F <sub>VTMPS</sub>	Temperature sensor that depends on the temperature		-3.6		mV/°C
Operation stabilization wait time	t <sub>AMP</sub>		5			μs

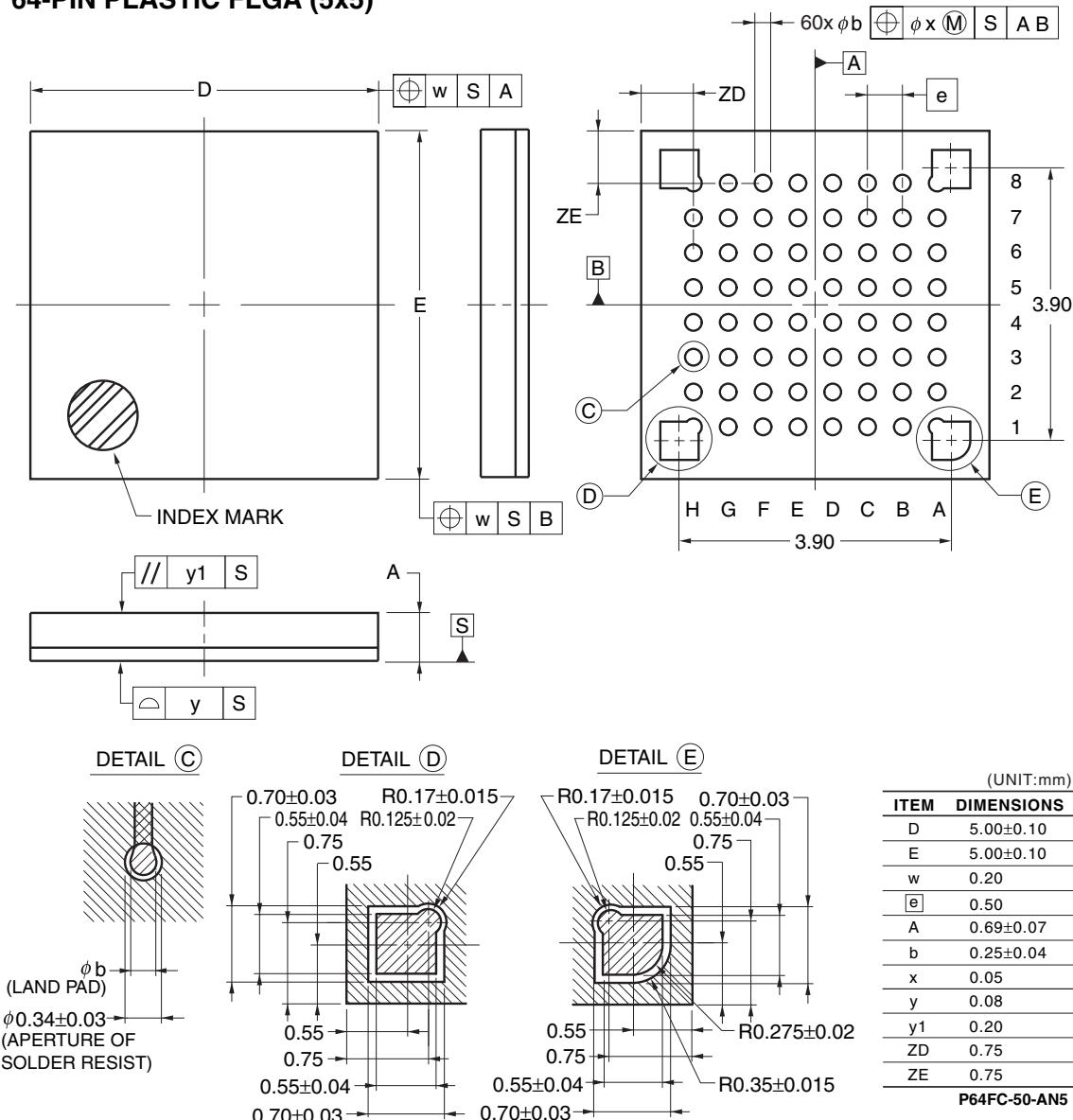
### 3.6.3 D/A converter characteristics

(TA = -40 to +105°C, 2.4 V ≤ EV<sub>SS0</sub> = EV<sub>SS1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES					8	bit
Overall error	AINL	R <sub>load</sub> = 4 MΩ	2.4 V ≤ V <sub>DD</sub> ≤ 5.5 V			±2.5	LSB
		R <sub>load</sub> = 8 MΩ	2.4 V ≤ V <sub>DD</sub> ≤ 5.5 V			±2.5	LSB
Settling time	t <sub>SET</sub>	C <sub>load</sub> = 20 pF	2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V			3	μs
			2.4 V ≤ V <sub>DD</sub> < 2.7 V			6	μs

R5F104LCALA, R5F104LDALA, R5F104LEALA, R5F104LFALA, R5F104LGALA, R5F104LHALA, R5F104LJALA  
 R5F104LKALA, R5F104LLALA  
 R5F104LCGLA, R5F104LDGLA, R5F104LEGGLA, R5F104LFGLA, R5F104LGGLA, R5F104LHGLA, R5F104LJGLA  
 R5F104LKGLA, R5F104LLGLA

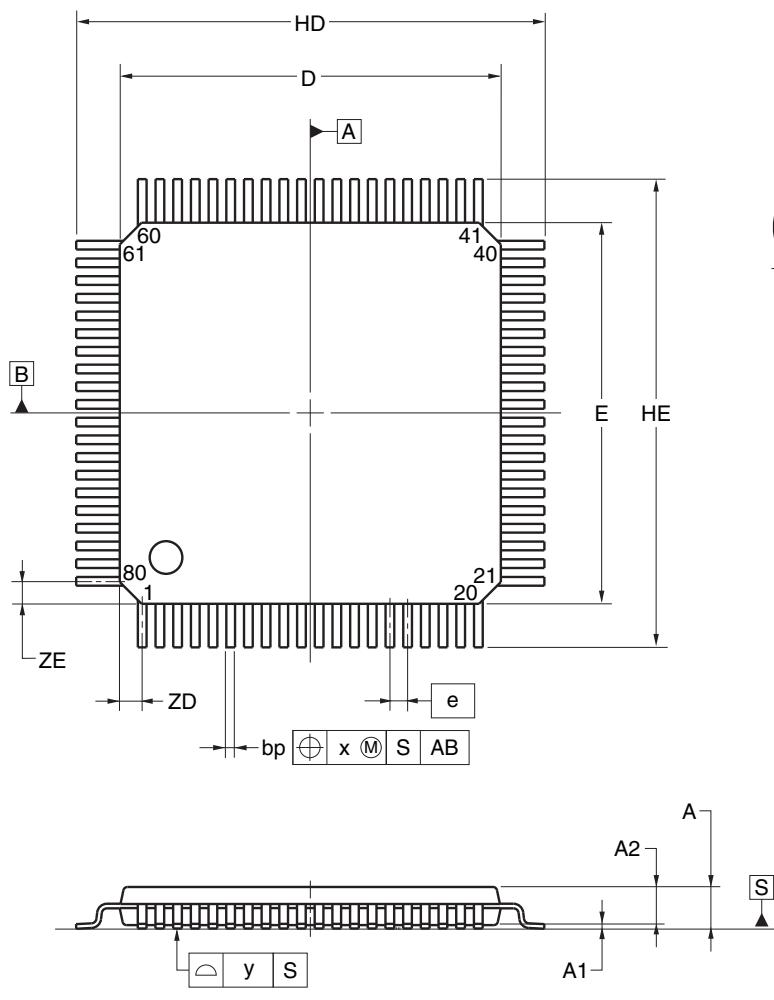
### 64-PIN PLASTIC FLGA (5x5)



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R5F104MFAFA, R5F104MGAFA, R5F104MHAFA, R5F104MJFA  
 R5F104MFDFA, R5F104MGDFA, R5F104MH DFA, R5F104MJDFA  
 R5F104MFGFA, R5F104MGGFA, R5F104MHGFA, R5F104MJGFA  
 R5F104MKAFA, R5F104MLAFA  
 R5F104MKGFA, R5F104MLGFA

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-LQFP80-14x14-0.65	PLQP0080JB-E	P80GC-65-UBT-2	0.69



Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.80	14.00	14.20
E	13.80	14.00	14.20
HD	17.00	17.20	17.40
HE	17.00	17.20	17.40
A	—	—	1.70
A1	0.05	0.125	0.20
A2	1.35	1.40	1.45
<b>A3</b>	—	0.25	—
bp	0.26	0.32	0.38
c	0.10	0.145	0.20
L	—	0.80	—
Lp	0.736	0.886	1.036
L1	1.40	1.60	1.80
theta	0°	3°	8°
<b>e</b>	—	0.65	—
x	—	—	0.13
y	—	—	0.10
ZD	—	0.825	—
ZE	—	0.825	—

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